

ABSTRACT OF THE DISCLOSURE

The present invention provides a light-receiving module that realized a reliable wire bonding from a light-receiving device to a die-capacitor on which the light-receiving device is mounted with adhesive. The light-

5 receiving module of the present invention includes a stem and a die-capacitor disposed on the set. The upper electrode of the die-capacitor has a mounting area where the light-receiving device is mounted, a bonding area to which the bonding-wire is to be bonded, and a structure for interrupting the adhesive from spreading from the mounting area to the bonding area. Since the

10 adhesive for die-bonding the light-receiving device in the mounting area does not spread to the bonding area, the wire-bonding to the bonding area can be reliably performed.